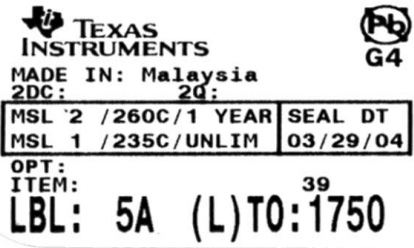



PCN Number:	20231220003.1	PCN Date:	December 21, 2023		
Title:	Qualification of RFAB as an additional Fab site option for select LBC9 devices				
Customer Contact:	Change Management team	Dept:	Quality Services		
Proposed 1st Ship Date:	Mar 20, 2024	Sample requests accepted until:	Jan 20, 2024*		
*Sample requests received after January 20, 2024 will not be supported.					
Change Type:					
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material			
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process			
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/> Wafer Fab Site			
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Material			
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process			
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
DMOS6	LBC9	300mm	RFAB	LBC9	300mm
Qual details are provided in the Qual Data Section.					
Reason for Change:					
Continuity of supply.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Fab Site Information:					
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
DMOS6	DM6	USA	Dallas		
RFAB	RFB	USA	Richardson		
Sample product shipping label (not actual product label)					
  <div style="float: right;"> (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CC0:USA (22L) AS0: MLA (23L) AC0: MYS </div>					
Product Affected:					
DRV8251ADDAR	DRV8251DDAR				

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV8251DDAR	QBS Reference: TLV62569DBVR	QBS Reference: DRV8251DDAR	QBS Reference: DRV8251DDAR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
UHA	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	3/231/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB Solder;	-	-	-	3/66/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	3/66/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	3/9/0	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	3/9/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: DRV8251DDAR	QBS Reference: TLV62569DBVR	QBS Reference: DRV8251DDAR	QBS Reference: DRV8251DDAR
ESD	E2	ESD HBM	-	4000 Volts	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	3/9/0	1/6/0	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	3/90/0	3/90/0	1/30/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	3/90/0	1/30/0

- QBS: Qual By Similarity
- Qual Device DRV8251DDAR is qualified at MSL3 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2202-081

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV8251ADDAR	QBS Reference: TLV62569DBVR	QBS Reference: DRV8251DDAR	QBS Reference: DRV8251DDAR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
UHA	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	3/231/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB Solder;	-	-	-	3/66/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	-	-	3/66/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	3/9/0	1/3/0	-

Type	#	Test Name	Condition	Duration	Qual Device: DRV8251ADDAR	QBS Reference: TLV62569DBVR	QBS Reference: DRV8251DDAR	QBS Reference: DRV8251DDAR
ESD	E2	ESD HBM	-	2000 Volts	-	3/9/0	1/3/0	-
ESD	E2	ESD HBM	-	4000 Volts	-	3/9/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	3/9/0	1/6/0	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	3/90/0	3/90/0	1/30/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	3/90/0	1/30/0

- QBS: Qual By Similarity
- Qual Device DRV8251ADDAR is qualified at MSL3 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2203-033

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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